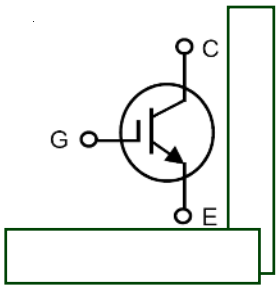
IXYS

GenX3™ 600V IGBT

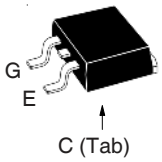
IXGA36N60A3
IXGP36N60A3
IXGH36N60A3

V_{CES} = 600V
I_{C110} = 36A
$V_{CE(sat)}$ ≤ 1.4V

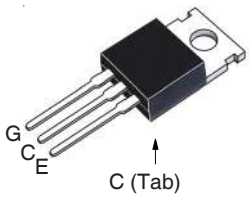
Ultra Low Vsat PT IGBT for up to 5kHz Switching



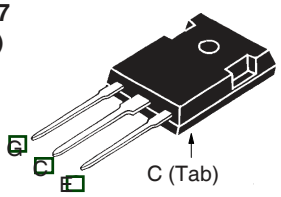
TO-263 (IXGA)



TO-220 (IXGP)



TO-247 (IXGH)



G = Gate C = Collector
E = Emitter Tab = Collector

Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T_C = 25°C to 150°C	600	V
V_{CGR}	T_J = 25°C to 150°C, R_{GE} = 1MΩ	600	V
V_{GES}	Continuous	± 20	V
V_{GEM}	Transient	± 30	V
I_{C25}	T_C = 25°C	96	A
I_{C110}	T_C = 110°C	36	A
I_{CM}	T_C = 25°C, 1ms	200	A
SSOA (RBSOA)	V_{GE} = 15V, T_{VJ} = 125°C, R_G = 5Ω Clamped Inductive Load	I_{CM} = 60 $V_{CE} \le V_{CES}$	A
P_C	T_C = 25°C	220	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	1.6 mm (0.062in.) from Case for 10s	260	°C
F_C	Mounting Force (TO-263)	10..65 / 2.2..14.6	N/lb
M_d	Mounting Torque (TO-220 & TO-247)	1.13 / 10	Nm/lb.in
Weight	TO-263	2.5	g
	TO-220	3.0	g
	TO-247	6.0	g

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{CES}	I_C = 250μA, V_{GE} = 0V	600			V
$V_{GE(th)}$	I_C = 250μA, V_{CE} = V_{GE}	3.0		5.5	V
I_{CES}	V_{CE} = V_{CES}, V_{GE} = 0V			25	μA
	T_J = 125°C			250	μA
I_{GES}	V_{CE} = 0V, V_{GE} = ±20V			±100	nA
$V_{CE(sat)}$	I_C = 30A, V_{GE} = 15V, Note 1			1.4	V

Features

- Optimized for Low Conduction Losses
- Square RBSOA
- International Standard Packages

Advantages

- High Power Density
- Low Gate Drive Requirement

Applications

- Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts
- Inrush Current Protection Circuits

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.
g_{fs}	I_C = 30A, V_{CE} = 10V, Note 1	25	42	S
C_{ies}	V_{CE} = 25V, V_{GE} = 0V, f = 1MHz		2380	pF
C_{oes}			115	pF
C_{res}			30	pF
Q_g	I_C = 30A, V_{GE} = 15V, V_{CE} = 0.5 • V_{CES}		80	nC
Q_{ge}			12	nC
Q_{gc}			36	nC
$t_{d(on)}$	**Inductive load, T_J = 25°C**		18	ns
t_{ri}	I_C = 30A, V_{GE} = 15V		23	ns
E_{on}	V_{CE} = 400V, R_G = 5Ω		0.74	mJ
$t_{d(off)}$	Note 2		330	ns
t_{fi}			325	ns
E_{off}			3.00	mJ
$t_{d(on)}$	**Inductive load, T_J = 125°C**		18	ns
t_{ri}	I_C = 30A, V_{GE} = 15V		25	ns
E_{on}	V_{CE} = 400V, R_G = 5Ω		1.50	mJ
$t_{d(off)}$	Note 2		500	ns
t_{fi}			500	ns
E_{off}			5.30	mJ
R_{thJC}				0.56 °C/W
R_{thCS}	TO-220		0.50	°C/W
	TO-247		0.21	°C/W

Notes:

1. Pulse test, t ≤ 300µs, duty cycle, d ≤ 2%.
2. Switching times & energy losses may increase for higher V_{CE}(clamp), T_J or R_G.

Fig. 1. Output Characteristics @ T_J = 25°C

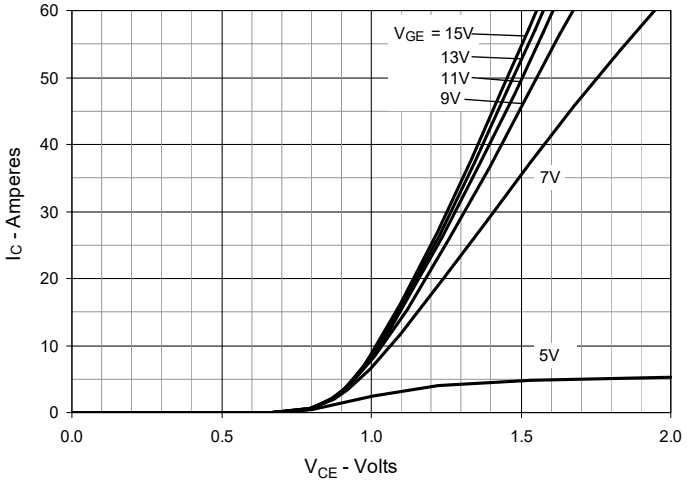


Fig. 2. Extended Output Characteristics @ T_J = 25°C

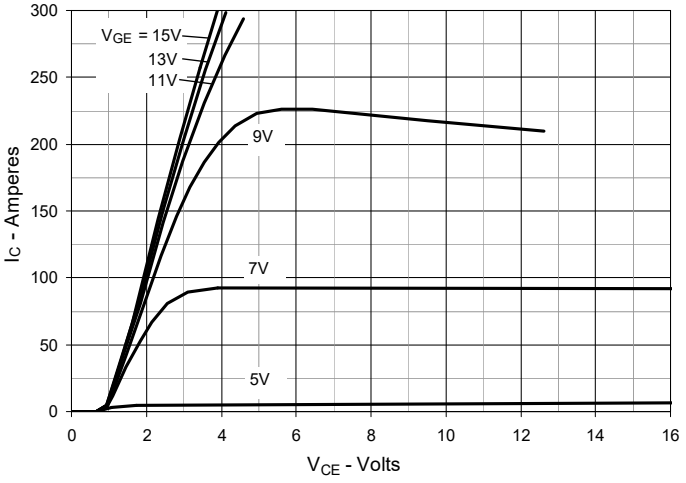


Fig. 3. Output Characteristics @ T_J = 125°C

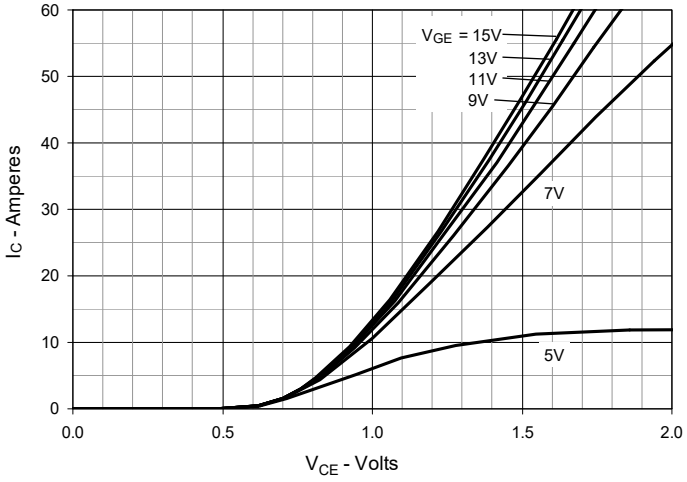


Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

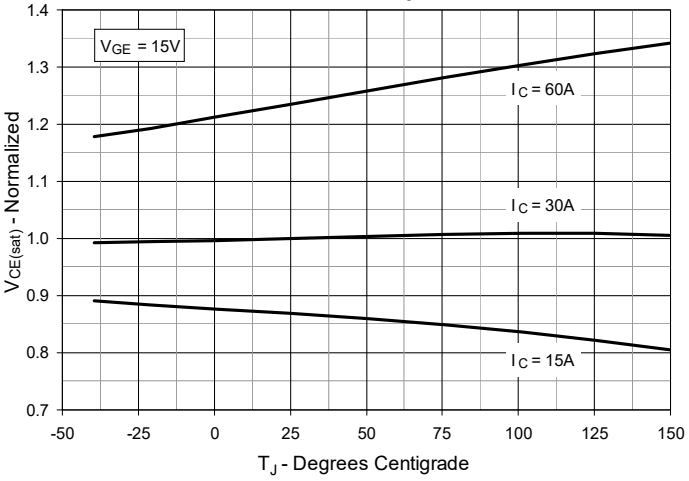


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

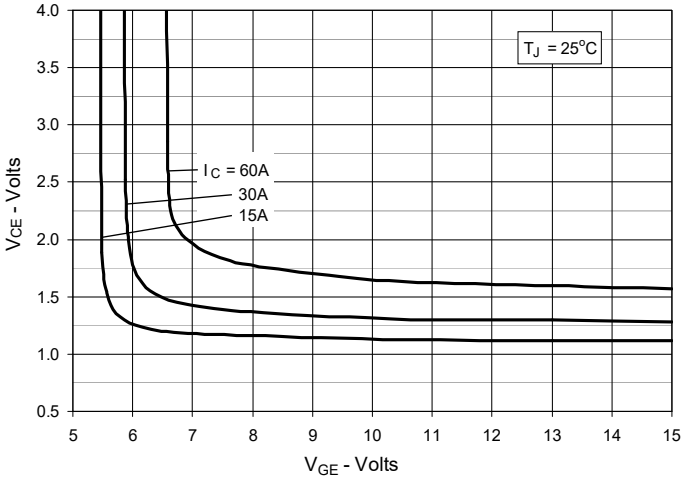


Fig. 6. Input Admittance

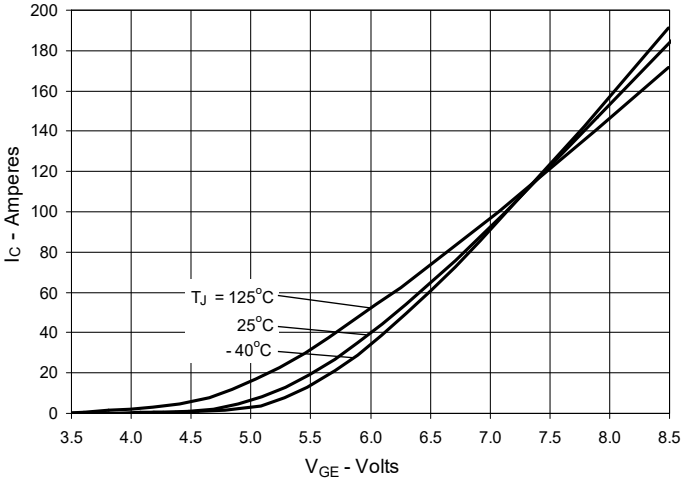


Fig. 7. Transconductance

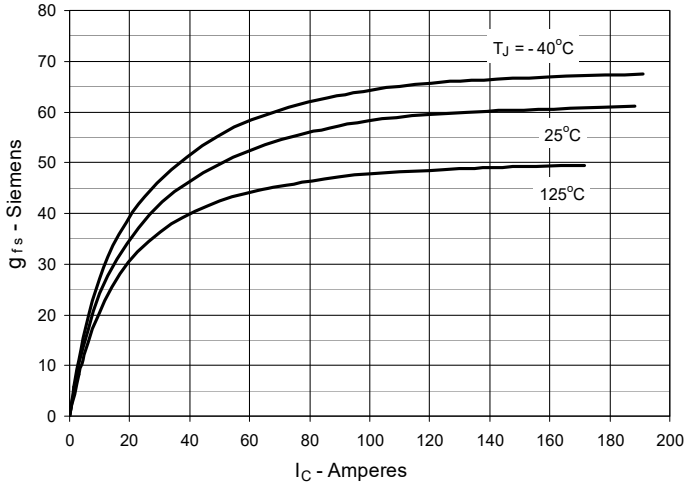


Fig. 8. Gate Charge

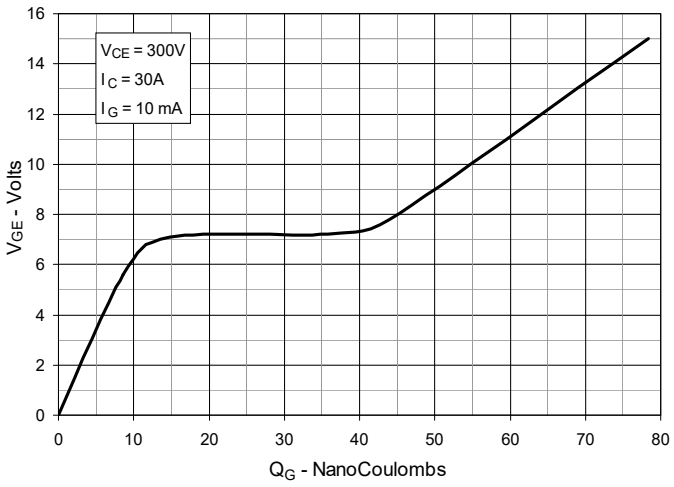


Fig. 9. Reverse-Bias Safe Operating Area

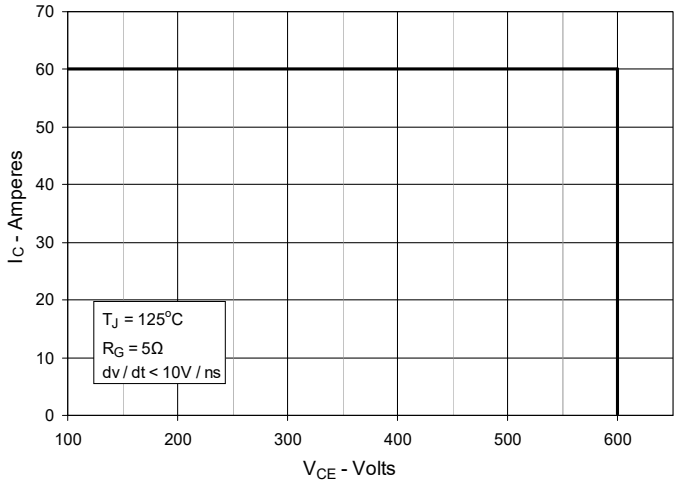


Fig. 10. Capacitance

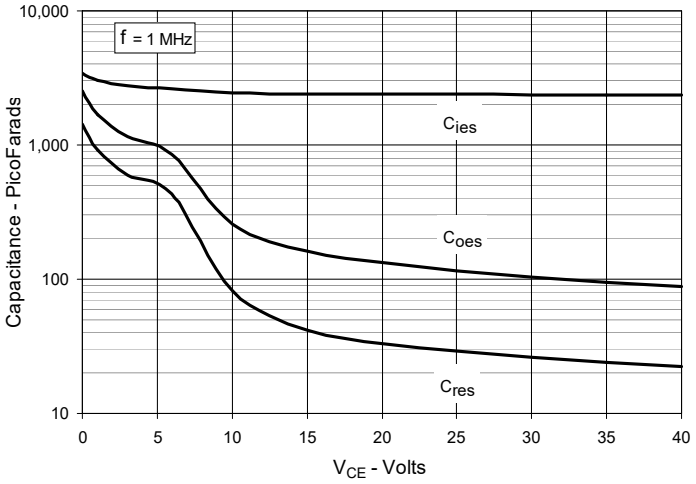


Fig. 11. Maximum Transient Thermal Impedance

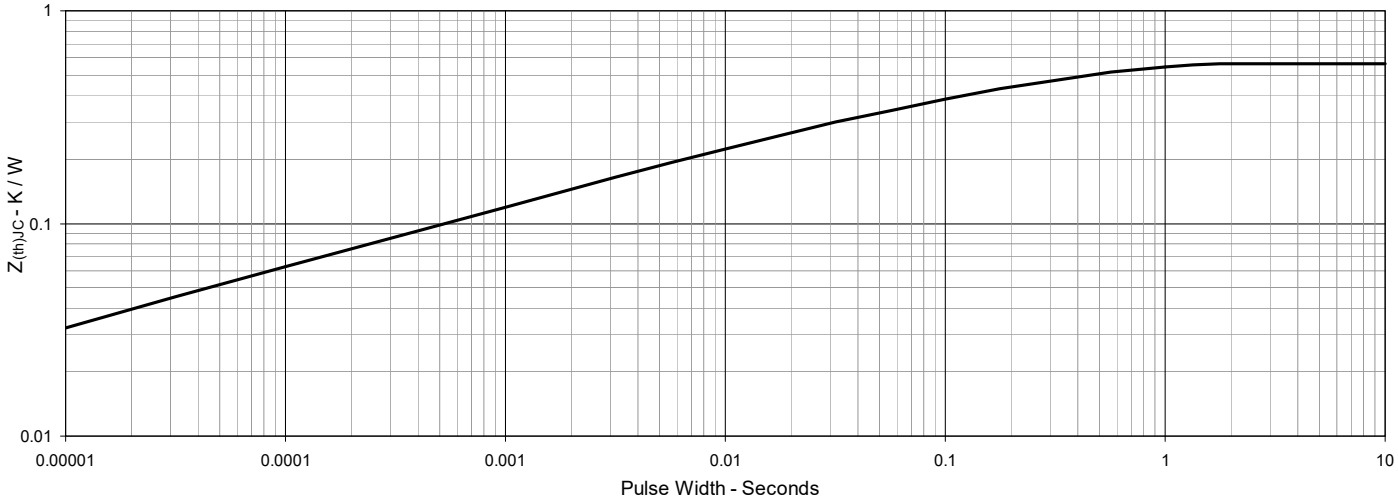


Fig. 12. Inductive Switching Energy Loss vs. Gate Resistance

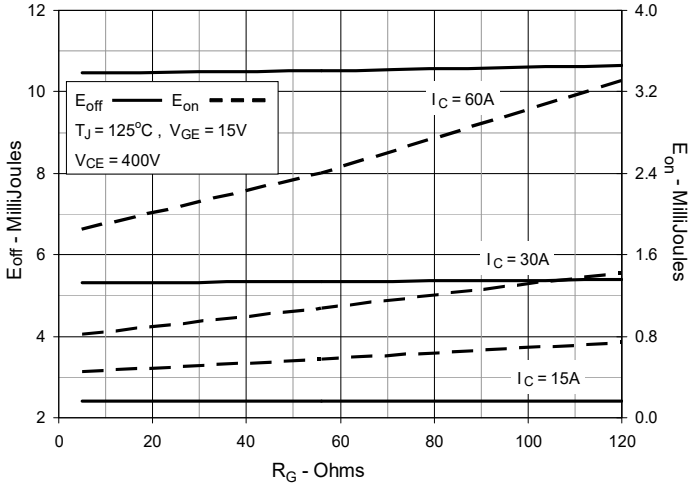


Fig. 13. Inductive Switching Energy Loss vs. Junction Temperature

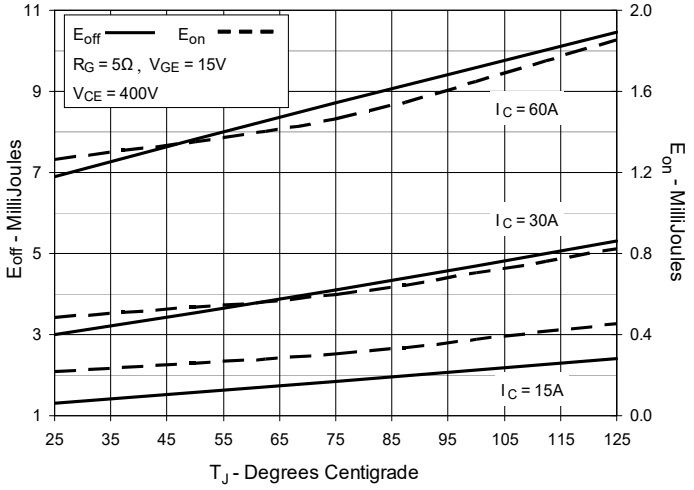


Fig. 14. Inductive Switching Energy Loss vs. Collector Current

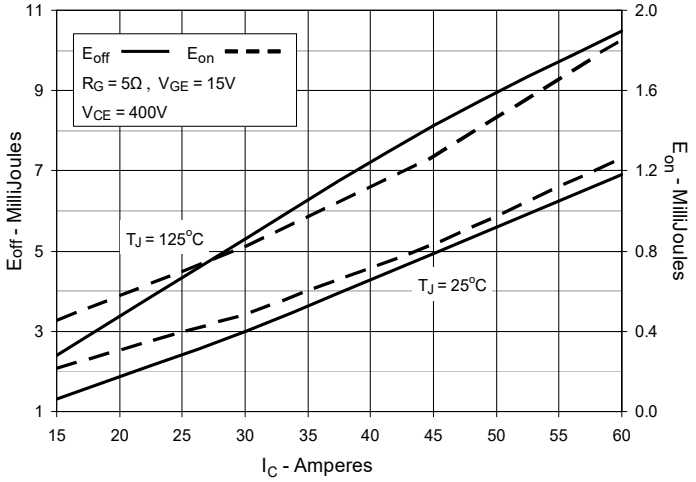


Fig. 15. Inductive Turn-off Switching Times vs. Gate Resistance

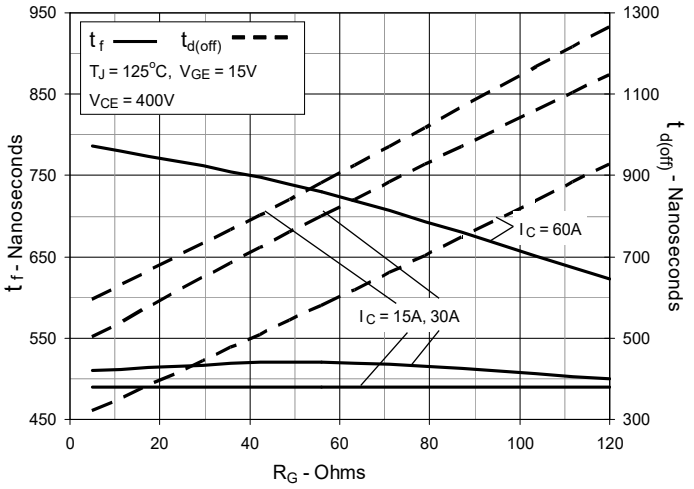


Fig. 16. Inductive Turn-off Switching Times vs. Collector Current

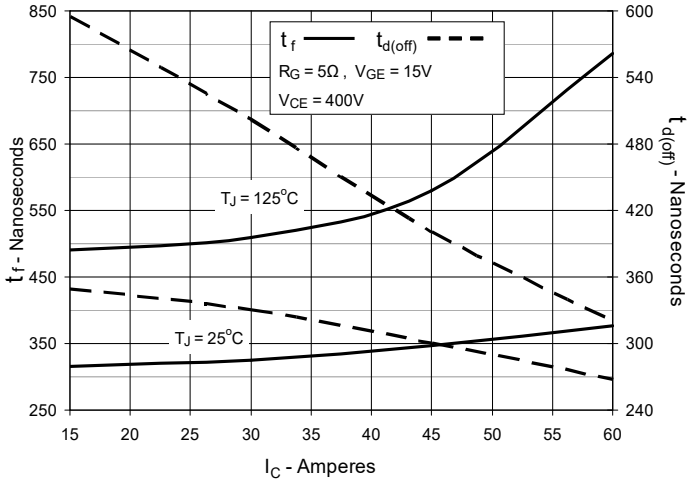


Fig. 17. Inductive Turn-off Switching Times vs. Junction Temperature

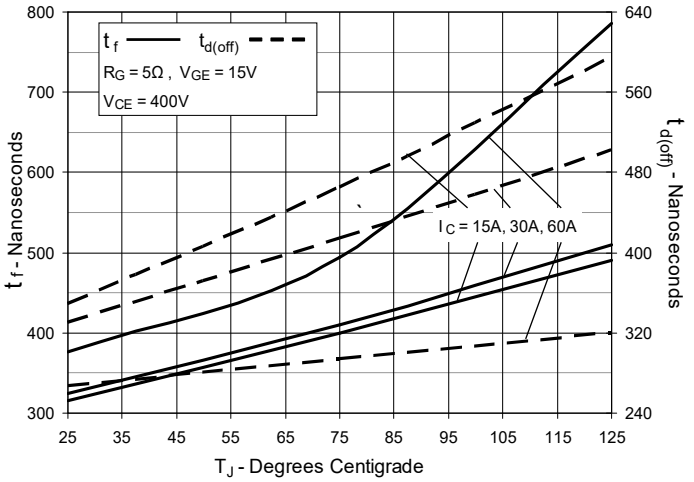


Fig. 18. Inductive Turn-on Switching Times vs. Gate Resistance

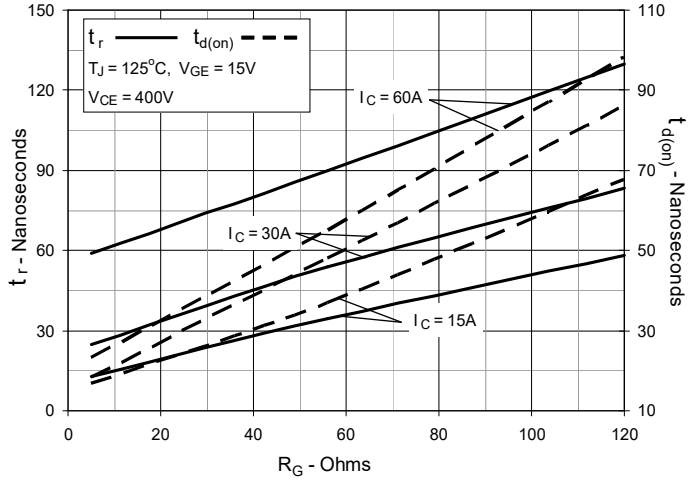


Fig. 19. Inductive Turn-on Switching Times vs. Junction Temperature

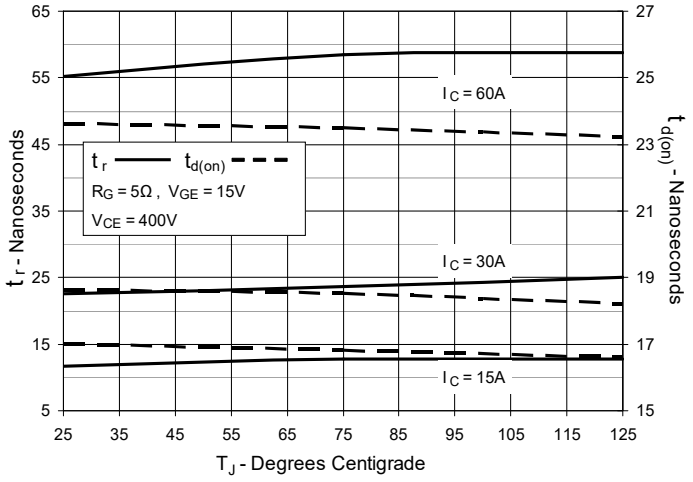
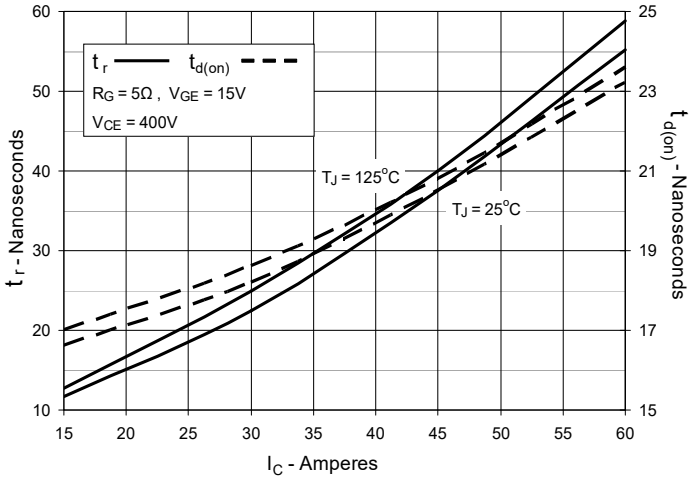
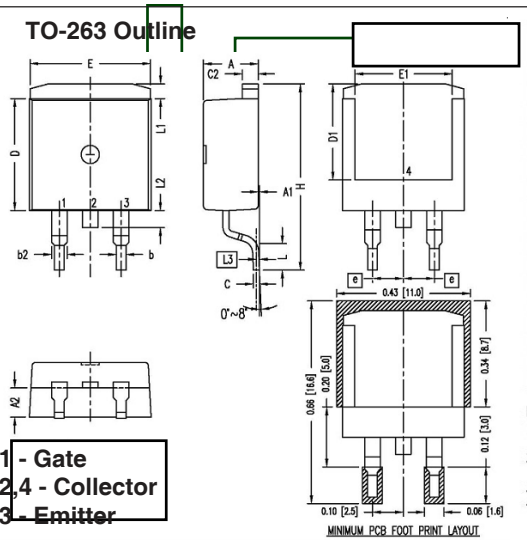


Fig. 20. Inductive Turn-on Switching Times vs. Collector Current



TO-263 Outline

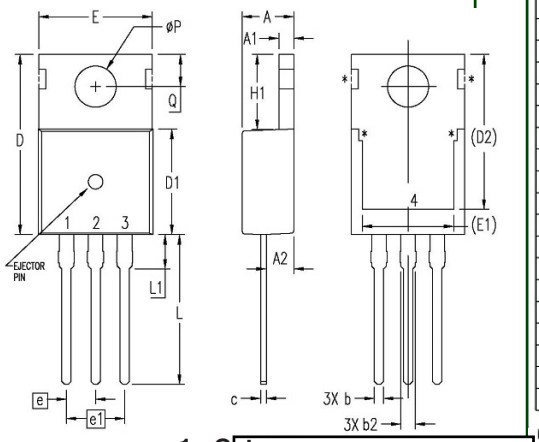


SYM	INCHES		MILLIMETER	
	MIN	MAX	MIN	MAX
A	.170	.185	4.30	4.70
A1	.000	.008	0.00	0.20
A2	.091	.098	2.30	2.50
b	.028	.035	0.70	0.90
b2	.046	.060	1.18	1.52
C	.018	.024	0.45	0.60
C2	.049	.060	1.25	1.52
D	.340	.370	8.63	9.40
D1	.300	.327	7.62	8.30
E	.380	.410	9.65	10.41
E1	.270	.330	6.86	8.38
e	.100 BSC		2.54 BSC	
H	.580	.620	14.73	15.75
L	.075	.105	1.91	2.67
L1	.039	.060	1.00	1.52
L2	—	.070	—	1.77
L3	.010 BSC		0.254 BSC	

NOTE:
1. This drawing meets all dimensions requirement of JEDEC outlines TO-263AB.
2. All metal surface are matte pure tin plated except trimmed area.
3. L3 is Gauge plane to measure L.
4. These dimension do not include mold flash and they will not exceed 0.005[0.13] per side.

1 - Gate
2,4 - Collector
3 - Emitter

TO-220 Outline

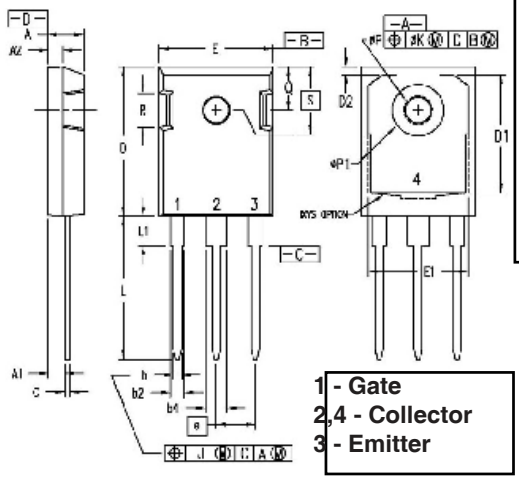


SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.169	.185	4.30	4.70
A1	.047	.055	1.20	1.40
A2	.079	.106	2.00	2.70
b	.024	.039	0.60	1.00
b2	.045	.057	1.15	1.45
c	.014	.026	0.35	0.65
D	.587	.626	14.90	15.90
D1	.335	.370	8.50	9.40
(D2)	.500	.531	12.70	13.50
E	.382	.406	9.70	10.30
(E1)	.283	.323	7.20	8.20
e	.100 BSC		2.54 BSC	
e1	.200 BSC		5.08 BSC	
H1	.244	.268	6.20	6.80
L	.492	.547	12.50	13.90
L1	.110	.154	2.80	3.90
øP	.134	.150	3.40	3.80
Q	.106	.126	2.70	3.20

NOTE:
1. These dimensions do not include mold protrusion.
2. Metal finish – Matte pure tin plating except trim area.
3. Tab call out: 1 – GATE; 3 – SOURCE (EMITTER for IGBT); 2 – DRAIN (COLLECTOR for IGBT); 4 – DRAIN (Connected with #2 internally)
4. Ejector pin location & diameter will vary depending on packaging suppliers.
5. * marked area will vary depending on packaging suppliers.

1 - Gate
2,4 - Collector
3 - Emitter

TO-247 Outline



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.190	.205	4.83	5.21
A1	.090	.100	2.29	2.54
A2	.075	.085	1.91	2.16
b	.045	.055	1.14	1.40
b2	.075	.087	1.91	2.20
b4	.115	.126	2.92	3.20
C	.024	.031	0.61	0.80
D	.819	.840	20.80	21.34
D1	.650	.690	16.51	17.53
D2	.035	.050	0.89	1.27
E	.620	.635	15.75	16.13
E1	.545	.565	13.84	14.35
e	.215 BSC		5.45 BSC	
J	--	.010	--	0.25
K	--	.025	--	0.64
L	.780	.810	19.81	20.57
L1	.150	.170	3.81	4.32
øP	.140	.144	3.55	3.65
øP1	.275	.290	6.99	7.37
Q	.220	.244	5.59	6.20
R	.170	.190	4.32	4.83
S	.242 BSC		6.15 BSC	

NOTE: This drawing will meet all dimensions requirement of JEDEC outlines TO-247 AD (R-PSIP-F3)

1 - Gate
2,4 - Collector
3 - Emitter